

L Number	Hits	Search Text	DB	Time stamp
1	15470	((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (slurry or composition)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 09:56
8	98	(((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (slurry or composition)) and (potassium adj iodate) and (copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 10:02
15	65	(((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (slurry or composition)) and (potassium adj iodate) and (copper)) and (((remov\$3 near2 rate\$1) or (polish\$3 near2 rate\$1)) same (copper or barrier))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 10:06